



SOT223

plastic surface-mounted package with increased heatsink; 4 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SC-73
Package type industry code	SC-73
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-73
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.3	-	6.5	6.7	mm
E	package width	3.3	-	3.5	3.7	mm
A	seated height	1.5	-	1.65	1.8	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

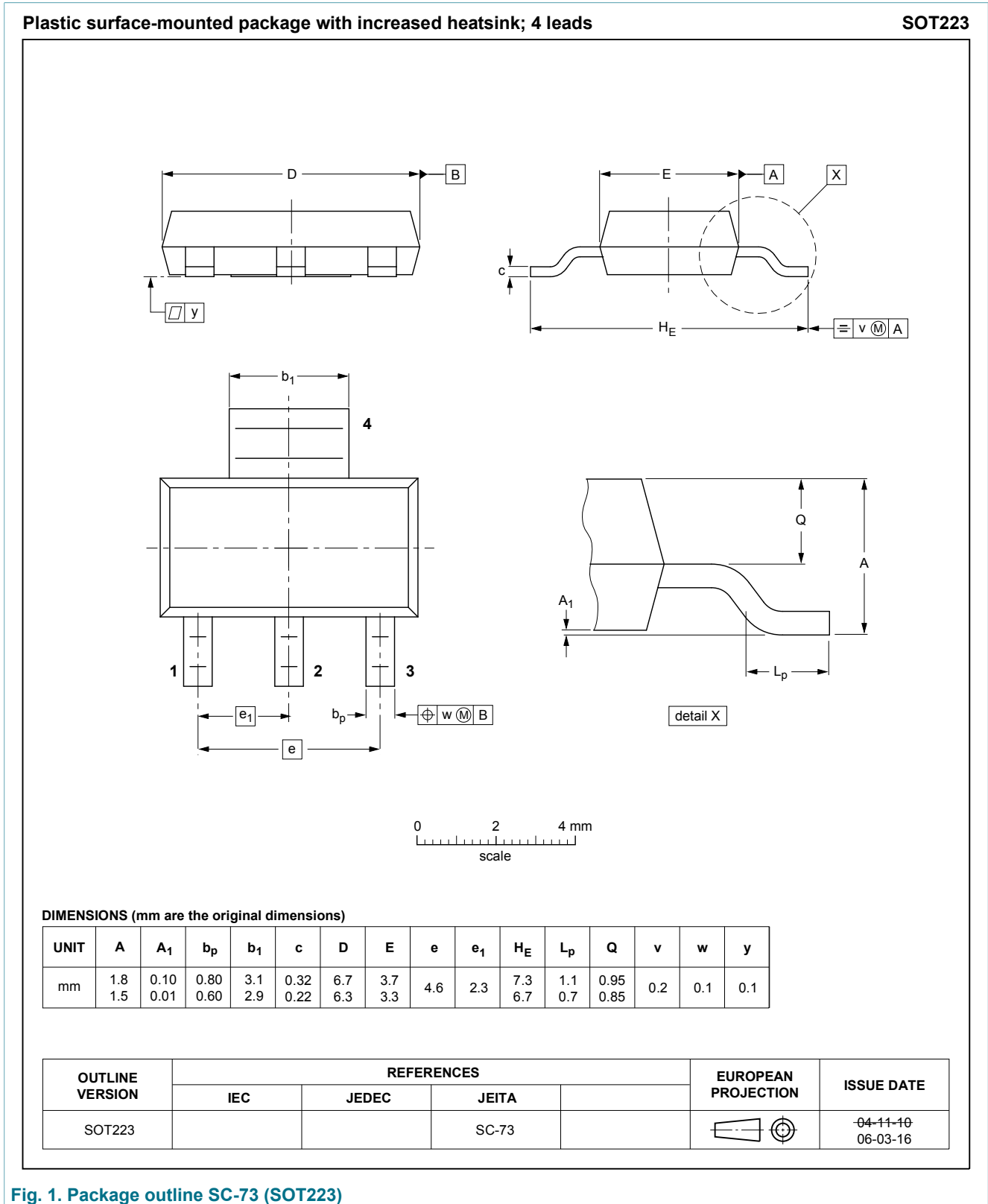


Fig. 1. Package outline SC-73 (SOT223)

3. Soldering

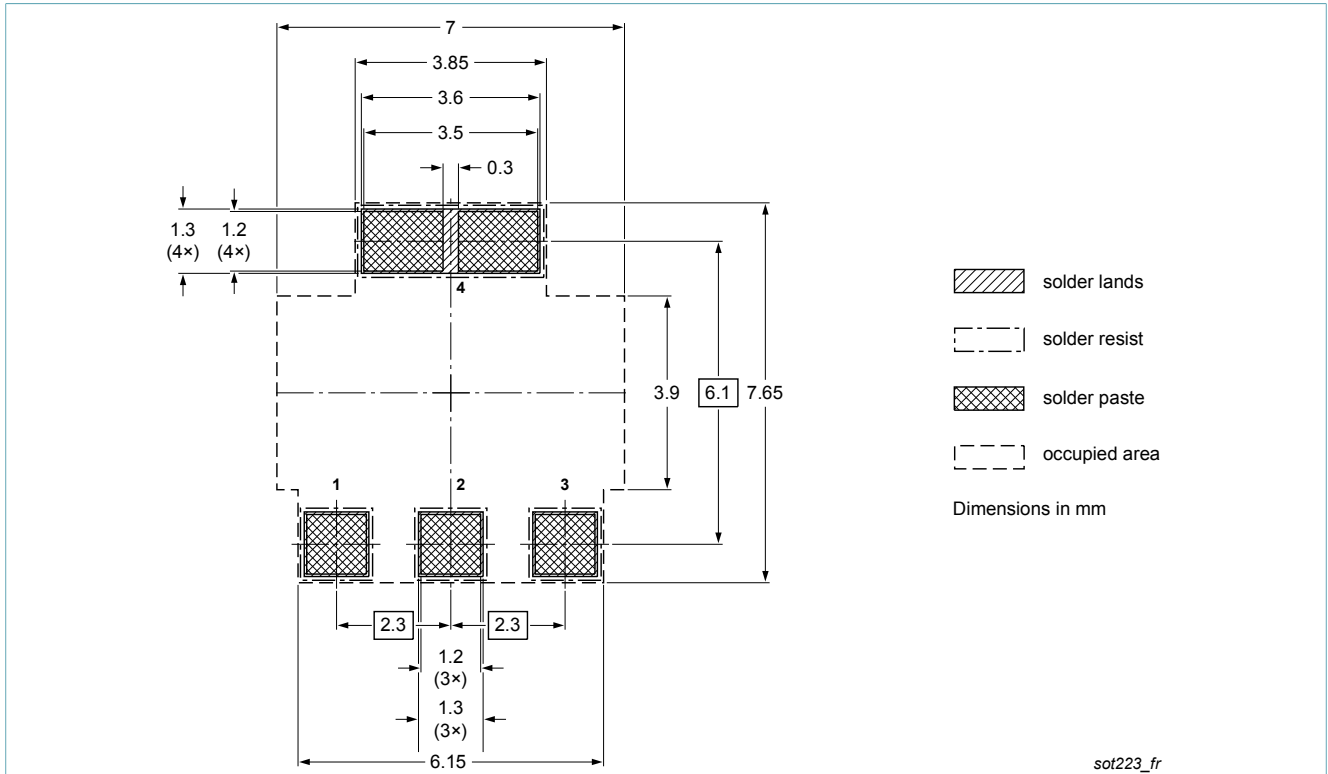


Fig. 2. Reflow soldering footprint for SC-73 (SOT223)

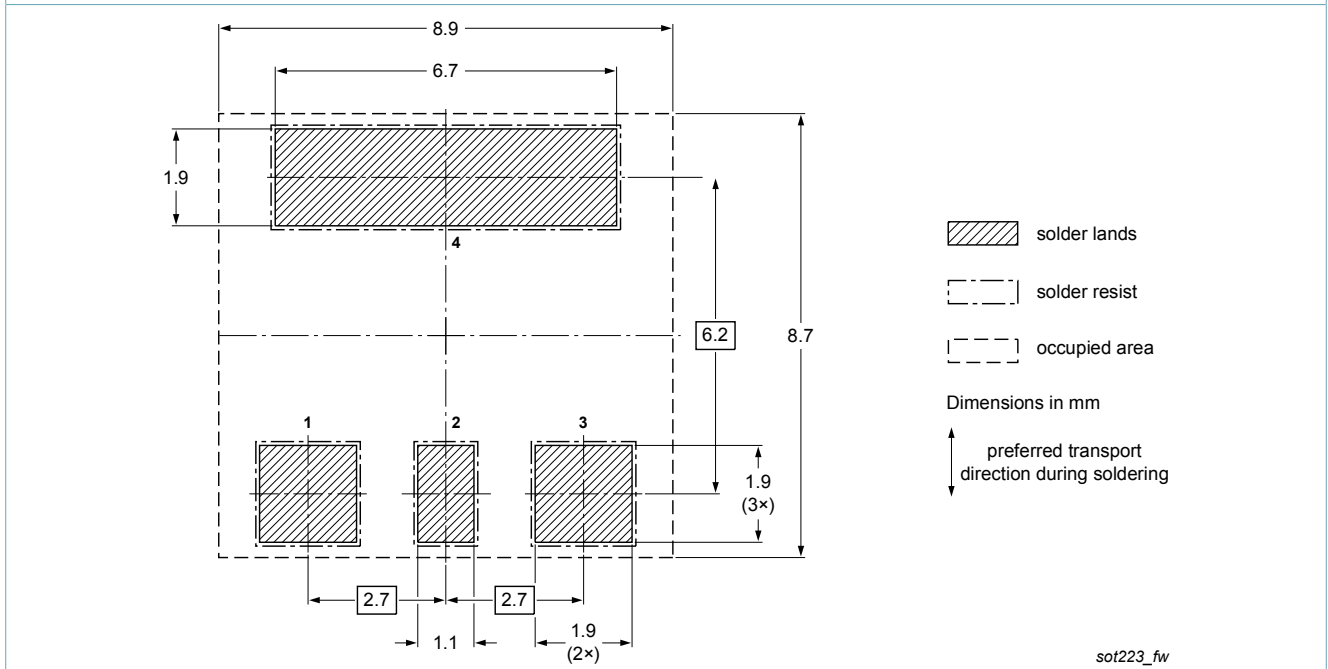


Fig. 3. Wave soldering footprint for SC-73 (SOT223)

4. Legal information

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